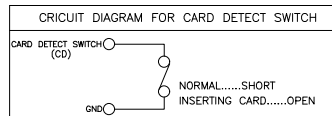


Printing instructio:
 YY MM DD
 DAY
 MONTH
 YEAR

NOTES:
 1.MATERIAL:
 HOUSING: High Temperature Thermoplastic
 Terminal:Copper Alloy
 Shell: Stainless Steel
 2.PLATING:
 Terminal:40u" Ni UNDERPLATED OVERALL
 G/F PLATED ON CONTACT AREA AND SOLDER AREA
 Shell:30u" Ni UNDERPLATED OVERALL
 G/F PLATED ON CONTACT AREA AND SOLDER AREA
 3.TECHNICAL SPECIALITY:
 RATED VOLTAGE: 30V AC MAX.
 CURRENT RATING: 0.5A MAX.
 INSULATION RESISTANCE:1000MΩ MIN
 CONTACT REISTANCE:50mΩ MAX
 WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
 OPERATING TEMPERATURE: -40℃~+85℃ Humidity 80% R.H MAX



PIIN/NO	ASSIGNMENT
P1	VCC
P2	RST
P3	CLK
P4	Reserved
P5	GND
P6	VPP
P7	I/O
P8	Reserved
P9	Detect Switch
P10	GND

RECOMMENDED PCB LAYOUT
 TOLERANCE:±0.05

- SMT SOLDER AREA
- COPPER RESTRICTED AREA
 1.TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
 2.NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA

MANUFACTURE DWG			东莞市讯普电子科技有限公司 DongGuan XunPu Electronics Co.,Ltd	
UNLESS OTHERWISE SPECIFIED TOLERANCES			TITLE: 2.0H 6+1Pin Push—Push SIM卡	
DECIMALS:	ANGLES:	PAR	SIM-134-ACP7	
.X:±0.30	X':±2'	DWN		
.XX:±0.20	X.X':±1'	CHKD		
.XXX:±0.10		APVD		
Website address		SCALE1:1	UNIT:MM	
		SIZE:A4	SHEET:1F1	REV:A